I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

The Colors Subspansed of Chapman & Chapman & Subspansed &

T-26-84 Date of Deposit

William A. Webb, Reg. No. 28,277

Name of Applicant, assignee or Registered Representative

Signature

Our Case No. 7103/30

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AMENI	OMENT GROUP 3200
	JUN - 8 1998
For Linear Polisher and Method for Semiconductor Wafer Planarization	RECENTED
Filing Date: May 8, 1997	) Group Art Unit No. 3203
Serial No.: 08/853,323	) Examiner: George Nguyen
Homayoun Talieh and David E. Weldon	
In re Application of:	)

**Assistant Commissioner for Patents** Washington, D.C. 20231

Dear Sir:

Please enter the following amendments in response to the Office Action of February 26, 1998.

## In the Claims

Please cancel Claims 1-22, 33 and 35 without prejudice, please amend Claims 32 and 34 as follows, and please enter new Claims 36-43 as follows:

(Amended) A polishing pad assembly for polishing a semiconductor 06/05/1998 ATWATER\_OSCADOD TO SEE THE COMPTISING: 328.00 QP

01 FC:102